FSA0620 Series

High Current Molded Power Inductors



FEATURES

- Powder iron core material
- Magnetically shielded, low EMI
- High current carrying capacity, Low core losses
- Frequency range up to 3MHz
- Operate temperature range -40° C \sim +125 $^{\circ}$ C (Including self temp. rise)
- RoHS compliant





APPLICATIONS

- Voltage Regulator Module (VRM)
- Multi-phase regulators
- Point-of-load modules
- Smart phone POL modules
- SSD modules
- Notebook regulators
- Battery power systems
- Graphics cards
- Data networking and storage systems

PRODUCT IDENTIFICATION

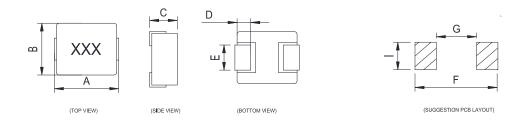
FSA0620 -1R0 M T

1 2 3 4 5

- ♦ 1:Product Series:Metal Alloy Molding Power Inductor
- ♦ 2:Dimensions:
- 3: Initial inductance value: 1R0 = 1.0uH
- ♦ 4:Tolerance of Inductance:M:±20%
- ♦ 5:Packing:Tape Carrier Package



Dimensions: [mm]



Series	Α	В	С	D	E	F Typ.	G Тур.	I Тур.
FSA0620	7.30Max	6.6±0.2	2.0 Max	1.6±0.3	3.0±0.3	8.40	3.7	3.5

Electrical Properties:

PART NO.	Ls	DCR (mΩ) MAX		Isat	Irms	TEST FREQ.
PART NO.	(uH)0A±20%	Тур	Max	dc(A) Typ	dc(A) Typ	(Hz)
FSA0620-R15MT	0.15	2.1	2.3	20	20	1M/1.0V
FSA0620-R22MT	0.22	3.8	4.3	18	15	1M/1.0V
FSA0620-R33MT	0.33	5.6	6.8	17	13	1M/1.0V
FSA0620-R47MT	0.47	6.7	7.9	16	12	1M/1.0V
FSA0620-R68MT	0.68	6.9	8.2	13	11	1M/1.0V
FSA0620-1R0MT	1.00	11.7	15.2	11.0	6.0	1M/1.0V
FSA0620-1R5MT	1.50	20.5	26.6	9.0	5.0	1M/1.0V
FSA0620-2R2MT	2.20	27.0	35.1	7.5	4.0	1M/1.0V
FSA0620-3R3MT	3.30	43	56	6.0	3.0	1M/1.0V
FSA0620-4R7MT	4.70	56	72	5.0	3.5	1M/1.0V
FSA0620-6R8MT	6.80	99	114	4.0	3.5	1M/1.0V
FSA0620-100MT	10.00	95	125	3.0	2.5	1M/1.0V
FSA0620-150MT	15.00	203	259	3.0	2.0	1M/1.0V
FSA0620-220MT	22.00	256	334	2.5	2.0	1M/1.0V

Notes

- %1: All test data is referenced to 20°C ambient;
- ※2: Rated current: Isat or Irms, whichever is smaller;
- ※3: Isat(Typ): DC current at which the inductance drops approximate 30% from its value without current;
- %4: Irms(Typ): DC current that causes the temperature rise (\triangle T =40°C) from 20°C ambient.
- %5: Absolute maximum voltage 30VDC

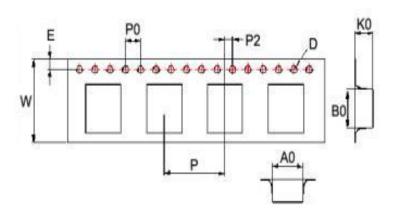


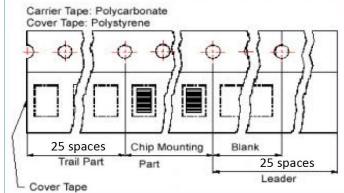
Reliability and Test Condition

Item	Specification and Requirement	Test Method				
	The surface of terminal immersed shall	Solder heat proof:				
Solderability	be minimum of 95% covered with a new	1. Preheating: 160 ± 10 ℃				
	coating of solder	2. Retention time: 245 ± 5 °C for 2 ± 0.5 seconds				
		Vibration frequency:				
	In the terms of the William A00/	(10 Hz to 55 Hz to 10Hz) in 60 seconds as a period				
\/ib=ation	Inductance change: Within ± 10%	2. Vibration time:				
Vibration	Without mechanical damage such as	Period cycled for 2 hours in each of 3 mutual				
	break	perpendicular directions.				
		3. Amplitude: 1.5 mm max.				
		1. Peak value: 100 G				
Shock	Inductance change: Within ±10% Without	2. Duration of pulse: 11ms				
SHOCK	mechanical damage such as break	3. 3 times in each positive and negative direction of 3				
		mutual perpendicular directions				
ndurance Relia	ability					
Item	Specification and Requirement	Test Method				
		1. Repeat 100 cycles as follow:				
	Inductance change: Within ± 10% Without distinct damage in appearance	(-55 ± 2 °C; 30 ± 3 min)				
Thermal		→(Room temp., 5 min)				
Shock		→ (+125 ± 2 °C, 30 ± 3 min)				
SHOCK		→ (Room temp., 5 min)				
		2. Recovery: 48 + 4 / -0 hours of recovery under the				
		standard condition after the test.				
High	Inductance change: Within ± 10%	1. Environment condition: 85 ± 2 ℃				
Temperature	Without distinct damage in appearance	Applied Current: Rated current				
Resistance	William distiller damage in appearance	2. Duration: 1000 + 4 / -0 hours				
		1. Environment condition: 60 ± 2 ℃				
Humidity	Inductance change: Within ± 10%	Humidity: 90–95%				
Resistance	Without distinct damage in appearance	Applied Current: Rated current				
		2. Duration: 1000 + 4 / -0 hours				
Low	Inductance change: Within ± 10%	Store temperature:				
Temperature	Without distinct damage in appearance	-55 ± 2 °C,1000 + 4 / -0 hours				
Store	The second secon	35 22 5,1555 17 6 116415				
High	Inductance change: Within ± 10%	Store temperature:				
Temperature	Without distinct damage in appearance	+125 ± 2 °C,1000 + 4 / -0 hours				
Store	annage in appearance					



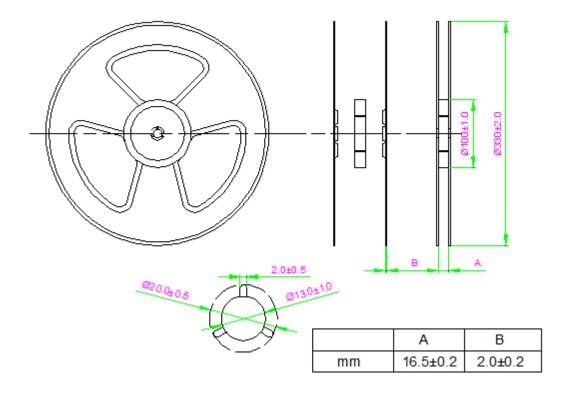
Tape Packaging Dimensions





Size	Ao(mm)	Bo(mm)	Ko(mm)	D(mm)	E(mm)	W(mm)	P(mm)	PO(mm)	P2(mm)
0620	10.6	11.7	2.2	1.55	1.75	16	12	4	2

Reel Dimensions



Packing Quantity:2000pcs/Reel



Recommended Soldering Technologies

(1) Re-flowing Profile

Preheat condition: 150 ~200 °C/60~180sec.

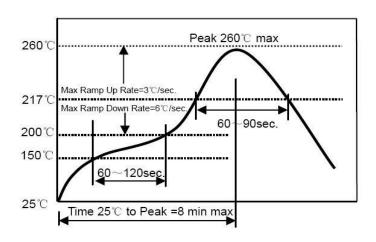
Allowed time above 217°C: 80~120sec.

Max temp: 260°C

Max time at max temp: 10 sec.

Solder paste: Sn/3.0Ag/0.5Cu

Allowed Reflow time: 2x max



(2) Iron Soldering Profile

Iron soldering power: Max.

30W Pre-heating: 150°C/60sec.

Soldering time: 3sec. Max.

Solder paste: Sn/3.0Ag/0.5Cu

Max.1 times for iron soldering

